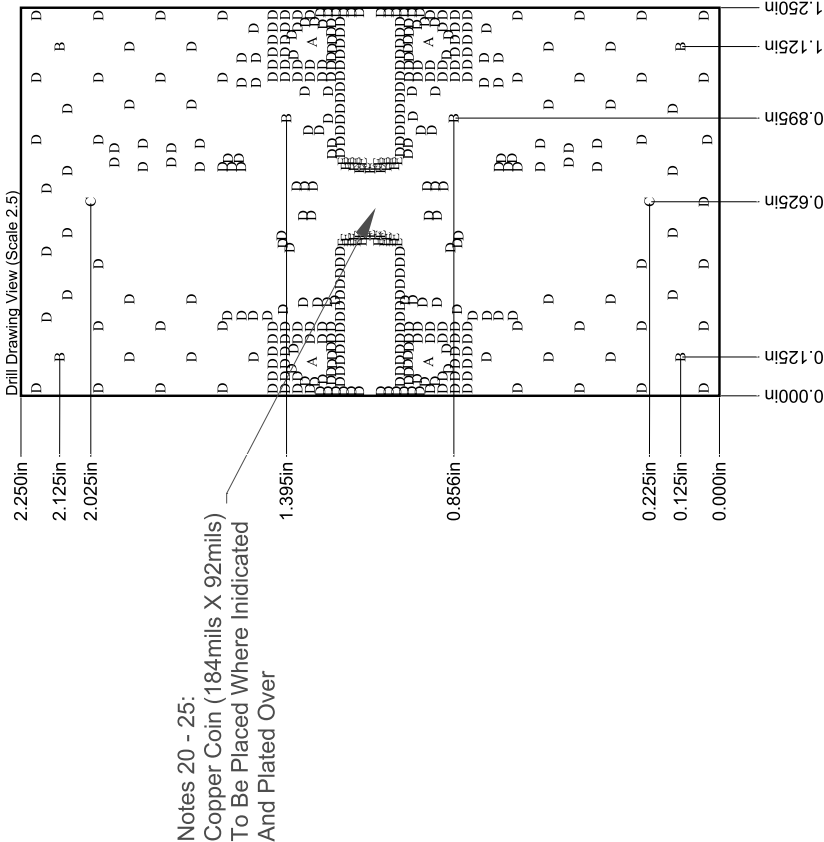


SUPPLIER MUST SEND EMAIL TO EVB@QORVO.COM IF JOB IS PLACED ON HOLD
SUPPLIER SHALL SEND A COPY OF FINAL WORKING GERBERS TO CEADS@QORVO.COM

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 2.
2. ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR
3. FINISH PLATING:
A. METAL 1 (TOP) AND METAL 4 (BOTTOM):
ENG (ELECTROLESS NICKEL/IMMERSION GOLD);
4. FINISHED BOARD THICKNESS: (SEE LAYER STACKUP) ±10%
5. CONTROLLED IMPEDANCE:
TARGET IMPEDANCE: 50 OHMS
MICROSTRIP LAYER: 1
IMPEDANCE TEST PER IPC-TM-650. IMPEDANCE TEST DATA TO BE DELIVERED WITH EACH LOT.
6. COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 1 (TOP) AND
METAL 4 (BOTTOM) METAL TO EDGE IS NECESSARY. THE PRODUCT PERFORMANCE IS SIGNIFICANTLY
COMPROMISED WITH LARGE PULL BACKS. WE WILL ACCEPT BURRS.
7. TOLERANCE: PCB BOARD OUTLINE:
A. PCB BOARD OUTLINE: ±0.003in. TOLERANCE AND IS CRITICAL TO RF PERFORMANCE
8. SINGULATION: EXTERNAL OF OUTLINE ARE TO BE COMPLETED
VIA OPTICAL (LENZ) ROUTING OR LASER TO ACHIEVE PCB OUTLINE TOLERANCE. LASER
ROUTING IS AUTHORIZED ONLY IF IT YIELDS A NON-CONTAMINATED SURFACE ADJACENT
TO THE LASER-SAWN EDGE.
9. METAL TO EDGE IS NECESSARY. THE PRODUCT PERFORMANCE IS SIGNIFICANTLY
COMPROMISED WITH LARGE PULL BACKS. WE WILL ACCEPT BURRS.
10. BURRS SHALL NOT EXCEED 0.002in.
11. VIA PLATING/FILLING:
A. ALL VIAS ARE TO BE EPOXY-FILLED, OVER-PLATED AND PLANARIZED
B. ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0007 ± 0.0004in. MIN. THICKNESS.
12. METAL 1 (TOP) AND METAL 4 (BOTTOM) AFTER OVERPLATING AND PLANARIZATION SHALL HAVE A MAX
ALLOWABLE NEGATIVE FEATURE OF 0.0008in. AND A MAX ALLOWABLE POSITIVE FEATURE OF 0.0003in.
13. FINISHED Cu THICKNESS TO BE .0018 ± .0005.
14. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.
15. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.
16. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.
17. NO VENDOR MARKING ALLOWED EXCEPT DATE CODE FOR TRACEABILITY.
18. BOARDS TO BE SINGULATED PER MECHANICAL 3 (OUTLINE) AND DELIVERED AS SINGLES
19. NO ELECTRICAL TEST IS NEEDED
20. FLATNESS AT COIN AREA TO BE FLUSH TO METAL 1 -0.000 TO +0.0014 PROTRUSION.
21. FLATNESS AT COIN AREA TO BE FLUSH TO METAL 4 WITHIN +0.0014/-0.001.
22. COPPER COIN APERTURE TO BE EDGE PLATED. METAL 1 AND METAL 4 TO BE
PLATED COMPLETELY ALONG COPPER APERTURE EDGE
23. COPPER COIN MATERIAL: OXYGEN FREE HIGH CONDUCTIVITY COPPER UWS CDA 101, 102, OR 103, ASTM B187, ASTM B152.
24. PLATING BETWEEN COPPER COIN AND METAL 1 & METAL 4 TO BE CONTINUOUS. (UNINTERRUPTED).
IF A SCALLOPED COIN IS USED, GAPS BETWEEN COIN AND PCB MUST BE FILLED.
25. TOP OF COPPER COIN TO BE PLATED TO METAL 1. BOTTOM OF COIN TO BE PLATED TO METAL 4.



REFERENCE NOTE: Uses QPA0017-4000[1] CAL SAP No. 301001

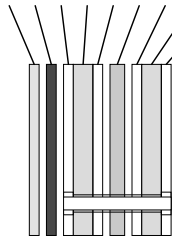
* FOR MULTIPLE DRILL PROCESS JOBS SEE: *DRL, *DR1, *DR2, etc.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES	SAP MATERIAL NUMBER: 303235		QORVO TM	
	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE		TITLE: QPA0016 EVALUATION PCB DESIGN PACKAGE	
INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009	DESIGNER ENGR.	DATE 12/1/2022	SIZE DOCUMENT NUMBER: B QPA0016-4000	PROTOTYPE INSTANCE: N/A A
	THIRD ANGLE PROJECTION		SHEET 1 OF 5 CAD: ALTIUM DESIGNER	
DO NOT SCALE DRAWING		SCALE: 2:1		

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FOR-001324 REV D

LAYER STACK LEGEND_(COPPER THICKNESS IS ~ FINISHED THICKNESS)



Material	Layer	Thickness	Dielectric Material	Type	Note
Surface Material	Top Overlay	0.0010in	Solder Resist	Legend	HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.
Copper	Top Solder	0.0020in		Solder Mask	LPI OR LDI, GREEN, MAX FINISH THICKNESS TO BE 0.001in.
Core	METAL1_TOP	0.0100in	TACONICS RF-35HTC	Signal	0.5oz. (Plus Plating)
Copper	METAL2_MID1	0.0006in		Signal	
Prepreg		0.0085in	370HR	Dielectric	
Copper	METAL3_MID2	0.0006in		Signal	
Core		0.0100in	370HR	Dielectric	
Copper	METAL4_BOT	0.0020in		Signal	0.5oz. (Plus Plating)

Total thickness: 0.0347in

NOTE: LPI (LIQUID PHOTO-IMAGEABLE) OR LDI (LASER DIRECT IMAGEABLE)

Drill Table (HOLE SIZES ARE DRILLED SIZE)

Symbol	Count	Hole Size	Plated	Drill Layer Pair
E	34	8.00mil(0.20mm)	Plated	METAL1_TOP - METAL4_BOT
D	358	10.00mil(0.25mm)	Plated	METAL1_TOP - METAL4_BOT
A	4	95.00mil(2.41mm)	Plated	METAL1_TOP - METAL4_BOT
B	6	100.00mil(2.54mm)	Plated	METAL1_TOP - METAL4_BOT
C	2	120.00mil(3.05mm)	Plated	METAL1_TOP - METAL4_BOT
	404 Total			

SIZE	DWG. NO.	PROTOTYPE	REV.
B	QPA0016-4000	N/A	A

SHEET 2 OF 5	CAD: ALTUM DESIGNER	SCALE: 2:1
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